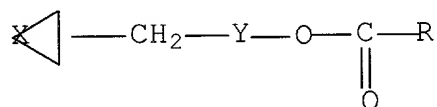


What Is Claimed Is:

1. A thermosetting resin composition, reaction products of which are controllably degradable, said composition comprising:

- (a) an epoxy resin component;
- (b) a curing agent component;
- (c) a coreactant, at least a portion of which

is represented by the following structure:



wherein X represents the heteroatoms, oxygen or sulfur; Y may or may not be present, and when present represents alkyl, alkenyl, or aryl; and R represents alkyl, alkenyl, or aryl; and

- (d) a stabilizer comprising a cyanate ester.

2. The composition of Claim 1, further comprising an inorganic filler component.

3. The composition of Claim 1, wherein the coreactant comprises glycidyl neodecanoate.

4. The composition of Claim 1, wherein the cyanate ester is selected from the group consisting of 1,3-dicyanatobenzene; 1,4-dicyanatobenzene; 1,3,5-tricyanatobenzene; 1,3-, 1,4-, 1,6-, 1,8-, 2,6- or 2,7-dicyanatonaphthalene; 1,3,6-tricyanatonaphthalene; 4,4'-dicyanato-biphenyl; bis(4-cyanatophenyl)methane; 2,2-bis(3,5-

dichloro-4-cyanatophenyl)propane; 2,2-bis(3,5-dibromo-4-dicyanatophenyl)propane; bis(4-cyanatophenyl)ether; bis(4-cyanatophenyl)sulfide; 2,2-bis(4-cyanatophenyl)propane; tris(4-cyanatophenyl)-phosphite; tris(4-cyanatophenyl)phosphate; bis(3-chloro-4-cyanatophenyl)methane; cyanated novolac; and cyanated bisphenol-terminated polycarbonate or other thermoplastic oligomer.

5. The composition of Claim 1, wherein the epoxy resin component includes bisphenol-A-type epoxy resin, bisphenol-F-type epoxy resin, phenol novolac-type epoxy resin, cresol novolac-type epoxy resin, polyepoxy compounds based on aromatic amines and epichlorohydrin, N-diglycidyl-4-aminophenyl glycidyl ether, N,N,N',N'-tetraglycidyl-1,3-propylene bis-4-aminobenzoate, polyglycidyl derivatives of phenolic compounds, polyepoxides prepared from polyols, polyglycidyl derivatives of phenol-formaldehyde novolacs, bisphenol-A-type epoxy novolacs, polyglycidyl adducts of amines, polyglycidyl adducts of aminoalcohols, polyglycidyl adducts of polycarboxylic acids, and combinations thereof.

6. The composition of Claim 1, wherein the epoxy resin component is present in the composition in an amount within the range of about 20% by weight to about 80% by weight, based on the total weight of the composition.

7. The composition of Claim 1, wherein the curing agent component is a member selected from the group consisting of anhydride compounds, aza compounds, amine compounds, amide compounds, imidazole compounds, modified amine compounds, modified imidazole compounds, cationic cure initiators and latent cationic cure initiators.

8. The composition of Claim 7, wherein the amine compounds are selected from the group consisting of aliphatic polyamines, aromatic polyamines, alicyclic polyamines and combinations thereof.

9. The composition of Claim 7, wherein the amine compounds are selected from the group consisting of diethylenetriamine, triethylenetetramine, diethylaminopropylamine, xylenediamine, diaminodiphenylamine, isophoronediamine, menthenediamine and combinations thereof.

10. The composition of Claim 7, wherein derivatives of the amine compounds include epoxy amine additives formed by the addition of an amine compound to an epoxy compound.

11. The composition of Claim 7, wherein derivatives of the amine compounds include "ANCAMINE" 2337S.

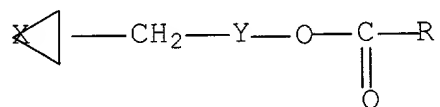
12. The composition of Claim 7, wherein derivatives of the amine compounds have an amine value of 260 (mg KOH/gram) and rapid reactivity above a temperature of 158°F.

13. The composition of Claim 7, wherein derivatives of the amine compounds are novolac-type resins modified through reaction with aliphatic amines.

14. The composition of Claim 7, wherein derivatives of the amine compounds are substantially insoluble at room temperature in non-basic, organic solvents.

15. A thermosetting resin composition, reaction products of which are controllably degradable, said composition comprising:

- (a) an epoxy resin component;
- (b) a curing agent component;
- (c) a coreactant, at least a portion of which is represented by the following structure:



wherein X represents the heteroatoms, oxygen or sulfur; Y may or may not be present, and when present represents alkyl, alkenyl, or aryl; and R represents alkyl, alkenyl, or aryl; and

- (d) a stabilizer comprising a cyanate ester, wherein the epoxy resin component is present in an amount in the range of from about 25 to about 75 percent by weight, the curing agent is "ANCAMINE" 2337S and is present in an amount within the range of from about 0.5 to about 5 percent by weight, the coreactant is glycidyl neodecanoate and is present in an amount of about 0.5 to about 5% by weight, and the stabilizer is a cyanate ester and is present in an amount of about 0.5 to about 5% by weight, based on the total composition.

16. The composition of Claim 1, which is capable of sealing underfilling between a semiconductor device including a semiconductor chip mounted on a carrier substrate and a circuit board to which said semiconductor device is electrically connected.

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17. Reaction products of the compositions in accordance with any one of Claims 1-16.

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